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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

Details

Product Status	Obsolete
Number of LABs/CLBs	6144
Number of Logic Elements/Cells	27648
Total RAM Bits	393216
Number of I/O	404
Number of Gates	1569178
Voltage - Supply	1.71V ~ 1.89V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	560-LBGA Exposed Pad, Metal
Supplier Device Package	560-MBGA (42.5x42.5)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xcv1000e-6bg560i

resources. The abundance of routing resources permits the Virtex-E family to accommodate even the largest and most complex designs.

Virtex-E FPGAs are SRAM-based, and are customized by loading configuration data into internal memory cells. Configuration data can be read from an external SPROM (master serial mode), or can be written into the FPGA (SelectMAP™, slave serial, and JTAG modes).

The standard Xilinx Foundation Series™ and Alliance Series™ Development systems deliver complete design support for Virtex-E, covering every aspect from behavioral and schematic entry, through simulation, automatic design translation and implementation, to the creation and downloading of a configuration bit stream.

Higher Performance

Virtex-E devices provide better performance than previous generations of FPGAs. Designs can achieve synchronous system clock rates up to 240 MHz including I/O or 622 Mb/s using Source Synchronous data transmission architectures. Virtex-E I/Os comply fully with 3.3 V PCI specifications, and interfaces can be implemented that operate at 33 MHz or 66 MHz.

While performance is design-dependent, many designs operate internally at speeds in excess of 133 MHz and can achieve over 311 MHz. **Table 2** shows performance data for representative circuits, using worst-case timing parameters.

Table 2: Performance for Common Circuit Functions

Function	Bits	Virtex-E (-7)
Register-to-Register		
Adder	16	4.3 ns
	64	6.3 ns
Pipelined Multiplier		
	8 x 8	4.4 ns
	16 x 16	5.1 ns
Address Decoder		
	16	3.8 ns
	64	5.5 ns
16:1 Multiplexer		4.6 ns
Parity Tree	9	3.5 ns
	18	4.3 ns
	36	5.9 ns
Chip-to-Chip		
HSTL Class IV		
LVTTL,16mA, fast slew		
LVDS		
LVPECL		

Virtex-E Device/Package Combinations and Maximum I/O

Table 3: Virtex-E Family Maximum User I/O by Device/Package (Excluding Dedicated Clock Pins)

	XCV 50E	XCV 100E	XCV 200E	XCV 300E	XCV 400E	XCV 600E	XCV 1000E	XCV 1600E	XCV 2000E	XCV 2600E	XCV 3200E
CS144	94	94	94								
PQ240	158	158	158	158	158						
HQ240						158	158				
BG352		196	260	260							
BG432				316	316	316					
BG560					404	404	404	404	404		
FG256	176	176	176	176							
FG456			284	312							
FG676					404	444					
FG680						512	512	512	512		
FG860							660	660	660		
FG900						512	660	700			
FG1156							660	724	804	804	804

Useful Application Examples

The Virtex-E DLL can be used in a variety of creative and useful applications. The following examples show some of the more common applications. The Verilog and VHDL example files are available at:

[ftp://ftp.xilinx.com/pub/applications/xapp/xapp132.zip](http://ftp.xilinx.com/pub/applications/xapp/xapp132.zip)

Standard Usage

The circuit shown in [Figure 27](#) resembles the BUFGDLL macro implemented to provide access to the RST and LOCKED pins of the CLKDLL.

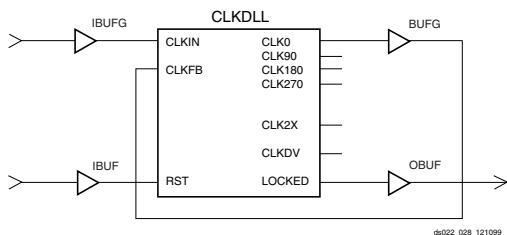


Figure 27: Standard DLL Implementation

Board Level Deskew of Multiple Non-Virtex-E Devices

The circuit shown in [Figure 28](#) can be used to deskew a system clock between a Virtex-E chip and other non-Virtex-E chips on the same board. This application is commonly used when the Virtex-E device is used in conjunction with other standard products such as SRAM or DRAM devices. While designing the board level route, ensure that the return net delay to the source equals the delay to the other chips involved.

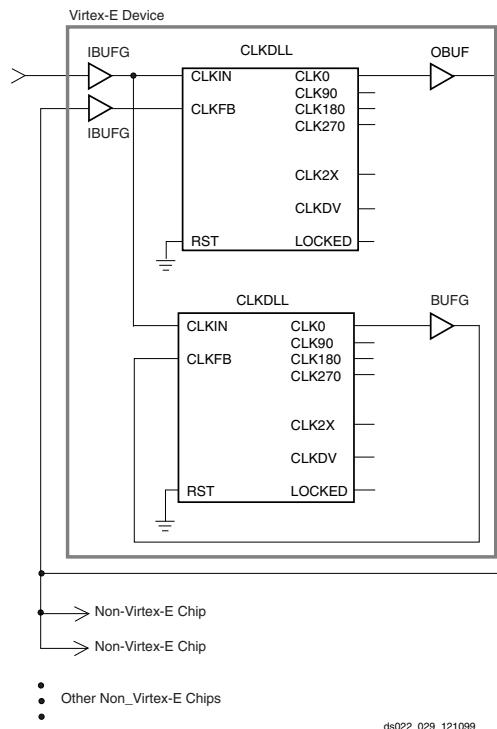


Figure 28: DLL Deskew of Board Level Clock

Board-level deskew is not required for low-fanout clock networks. It is recommended for systems that have fanout limitations on the clock network, or if the clock distribution chip cannot handle the load.

Do not use the DLL output clock signals until after activation of the LOCKED signal. Prior to the activation of the LOCKED signal, the DLL output clocks are not valid and can exhibit glitches, spikes, or other spurious movement.

The `dll_mirror_1` files in the [xapp132.zip](#) file show the VHDL and Verilog implementation of this circuit.

Deskew of Clock and Its 2x Multiple

The circuit shown in [Figure 29](#) implements a 2x clock multiplier and also uses the CLK0 clock output with a zero ns skew between registers on the same chip. Alternatively, a clock divider circuit can be implemented using similar connections.

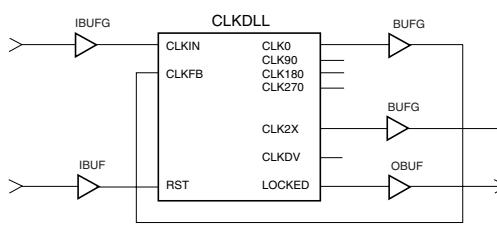


Figure 29: DLL Deskeew of Clock and 2x Multiple

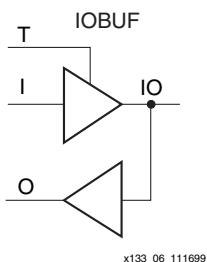


Figure 42: Input/Output Buffer Symbol (IOBUF)

The following list details variations of the IOBUF symbol.

- IOBUF
- IOBUF_S_2
- IOBUF_S_4
- IOBUF_S_6
- IOBUF_S_8
- IOBUF_S_12
- IOBUF_S_16
- IOBUF_S_24
- IOBUF_F_2
- IOBUF_F_4
- IOBUF_F_6
- IOBUF_F_8
- IOBUF_F_12
- IOBUF_F_16
- IOBUF_F_24
- IOBUF_LVCMOS2
- IOBUF_PCI33_3
- IOBUF_PCI66_3
- IOBUF_GTL
- IOBUF_GTL_P
- IOBUF_HSTL_I
- IOBUF_HSTL_III
- IOBUF_HSTL_IV
- IOBUF_SSTL3_I
- IOBUF_SSTL3_II
- IOBUF_SSTL2_I
- IOBUF_SSTL2_II
- IOBUF_CTT
- IOBUF_AG
- IOBUF_LVCMOS18
- IOBUF_LVDS
- IOBUF_LVPECL

When the IOBUF symbol used supports an I/O standard that requires a differential amplifier input, the IOBUF automatically configures with a differential amplifier input buffer.

The low-voltage I/O standards with a differential amplifier input require an external reference voltage input V_{REF}

The voltage reference signal is “banked” within the Virtex-E device on a half-edge basis such that for all packages there are eight independent V_{REF} banks internally. See [Figure 38, page 34](#) for a representation of the Virtex-E I/O banks. Within each bank approximately one of every six I/O pins is automatically configured as a V_{REF} input. After placing a differential amplifier input signal within a given V_{REF} bank, the same external source must drive all I/O pins configured as a V_{REF} input.

IOBUF placement restrictions require any differential amplifier input signals within a bank be of the same standard.

The Virtex-E series supports eight banks for the HQ and PQ packages. The CS package supports four V_{CCO} banks.

Additional restrictions on the Virtex-E SelectI/O IOBUF placement require that within a given V_{CCO} bank each IOBUF must share the same output source drive voltage. Input buffers of any type and output buffers that do not require V_{CCO} can be placed within the same V_{CCO} bank. The LOC property can specify a location for the IOBUF.

An optional delay element is associated with the input path in each IOBUF. When the IOBUF drives an input flip-flop within the IOB, the delay element activates by default to ensure a zero hold-time requirement. Override this default with the NODELAY=TRUE property.

In the case when the IOBUF does not drive an input flip-flop within the IOB, the delay element de-activates by default to provide higher performance. To delay the input signal, activate the delay element with the DELAY=TRUE property.

3-state output buffers and bidirectional buffers can have either a weak pull-up resistor, a weak pull-down resistor, or a weak “keeper” circuit. Control this feature by adding the appropriate symbol to the output net of the IOBUF (PULLUP, PULLDOWN, or KEEPER).

SelectI/O Properties

Access to some of the SelectI/O features (for example, location constraints, input delay, output drive strength, and slew rate) is available through properties associated with these features.

Input Delay Properties

An optional delay element is associated with each IBUF. When the IBUF drives a flip-flop within the IOB, the delay element activates by default to ensure a zero hold-time requirement. Use the NODELAY=TRUE property to override this default.

In the case when the IBUF does not drive a flip-flop within the IOB, the delay element by default de-activates to provide higher performance. To delay the input signal, activate the delay element with the DELAY=TRUE property.

Table 21: Guidelines for Max Number of Simultaneously Switching Outputs per Power/Ground Pair (Continued)

Standard	Package		
	BGA, CS, FGA	HQ	PQ, TQ
HSTL Class I	18	13	9
HSTL Class III	9	7	5
HSTL Class IV	5	4	3
SSTL2 Class I	15	11	8
SSTL2 Class II	10	7	5
SSTL3 Class I	11	8	6
SSTL3 Class II	7	5	4
CTT	14	10	7
AGP	9	7	5

Note: This analysis assumes a 35 pF load for each output.

Table 22: Virtex-E Equivalent Power/Ground Pairs

Pkg/Part	XCV100E	XCV200E	XCV300E	XCV400E	XCV600E	XCV1000E	XCV1600E	XCV2000E
CS144	12	12						
PQ240	20	20	20	20				
HQ240					20	20		
BG352	20	32	32					
BG432			32	40	40			
BG560				40	40	56	58	60
FG256 ⁽¹⁾	20	24	24					
FG456		40	40					
FG676				54	56			
FG680 ⁽²⁾					46	56	56	56
FG860						58	60	64
FG900					56	58		60
FG1156						96	104	120

Notes:

1. Virtex-E devices in FG256 packages have more V_{CCO} than Virtex series devices.
2. FG680 numbers are preliminary.

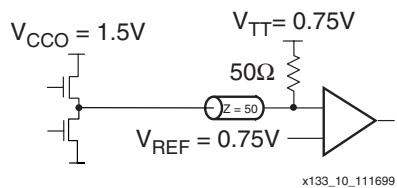
HSTL

A sample circuit illustrating a valid termination technique for HSTL_I appears in [Figure 46](#). A sample circuit illustrating a valid termination technique for HSTL_III appears in [Figure 47](#).

Table 25: HSTL Class I Voltage Specification

Parameter	Min	Typ	Max
V_{CCO}	1.40	1.50	1.60
V_{REF}	0.68	0.75	0.90
V_{TT}	-	$V_{CCO} \times 0.5$	-
V_{IH}	$V_{REF} + 0.1$	-	-
V_{IL}	-	-	$V_{REF} - 0.1$
V_{OH}	$V_{CCO} - 0.4$	-	-
V_{OL}			0.4
I_{OH} at V_{OH} (mA)	-8	-	-
I_{OL} at V_{OL} (mA)	8	-	-

HSTL Class I



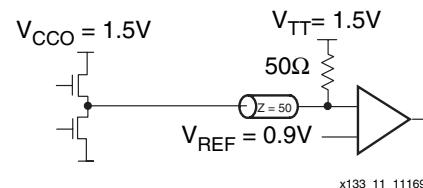
[Figure 46: Terminated HSTL Class I](#)

Table 26: HSTL Class III Voltage Specification

Parameter	Min	Typ	Max
V_{CCO}	1.40	1.50	1.60
V_{REF} ⁽¹⁾	-	0.90	-
V_{TT}	-	V_{CCO}	-
V_{IH}	$V_{REF} + 0.1$	-	-
V_{IL}	-	-	$V_{REF} - 0.1$
V_{OH}	$V_{CCO} - 0.4$	-	-
V_{OL}	-	-	0.4
I_{OH} at V_{OH} (mA)	-8	-	-
I_{OL} at V_{OL} (mA)	24	-	-

Note: Per EIA/JESD8-6, "The value of V_{REF} is to be selected by the user to provide optimum noise margin in the use conditions specified by the user."

HSTL Class III



[Figure 47: Terminated HSTL Class III](#)

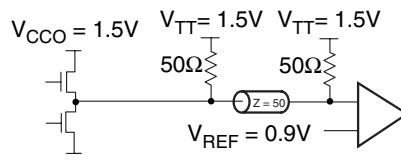
A sample circuit illustrating a valid termination technique for HSTL_IV appears in [Figure 48](#).

Table 27: HSTL Class IV Voltage Specification

Parameter	Min	Typ	Max
V_{CCO}	1.40	1.50	1.60
V_{REF}	-	0.90	-
V_{TT}	-	V_{CCO}	-
V_{IH}	$V_{REF} + 0.1$	-	-
V_{IL}	-	-	$V_{REF} - 0.1$
V_{OH}	$V_{CCO} - 0.4$	-	-
V_{OL}	-	-	0.4
I_{OH} at V_{OH} (mA)	-8	-	-
I_{OL} at V_{OL} (mA)	48	-	-

Note: Per EIA/JESD8-6, "The value of V_{REF} is to be selected by the user to provide optimum noise margin in the use conditions specified by the user."

HSTL Class IV



[Figure 48: Terminated HSTL Class IV](#)

Date	Version	Revision
9/20/00	1.7	<ul style="list-style-type: none"> Min values added to Virtex-E Electrical Characteristics tables. XCV2600E and XCV3200E numbers added to Virtex-E Electrical Characteristics tables (Module 3). Corrected user I/O count for XCV100E device in Table 1 (Module 1). Changed several pins to “No Connect in the XCV100E” and removed duplicate V_{CCINT} pins in Table ~ (Module 4). Changed pin J10 to “No connect in XCV600E” in Table 74 (Module 4). Changed pin J30 to “VREF option only in the XCV600E” in Table 74 (Module 4). Corrected pair 18 in Table 75 (Module 4) to be “AO in the XCV1000E, XCV1600E”.
11/20/00	1.8	<ul style="list-style-type: none"> Upgraded speed grade -8 numbers in Virtex-E Electrical Characteristics tables to Preliminary. Updated minimums in Table 13 and added notes to Table 14. Added to note 2 to Absolute Maximum Ratings. Changed speed grade -8 numbers for $T_{SHCKO32}$, T_{REG}, T_{BCCS}, and T_{ICKOF}. Changed all minimum hold times to -0.4 under Global Clock Set-Up and Hold for LVTTL Standard, with DLL. Revised maximum T_{DLLPW} in -6 speed grade for DLL Timing Parameters. Changed GCLK0 to BA22 for FG860 package in Table 46.
2/12/01	1.9	<ul style="list-style-type: none"> Revised footnote for Table 14. Added numbers to Virtex-E Electrical Characteristics tables for XCV1000E and XCV2000E devices. Updated Table 27 and Table 78 to include values for XCV400E and XCV600E devices. Revised Table 62 to include pinout information for the XCV400E and XCV600E devices in the BG560 package. Updated footnotes 1 and 2 for Table 76 to include XCV2600E and XCV3200E devices.
4/02/01	2.0	<ul style="list-style-type: none"> Updated numerous values in Virtex-E Switching Characteristics tables. Converted data sheet to modularized format. See the Virtex-E Data Sheet section.
4/19/01	2.1	<ul style="list-style-type: none"> Modified Figure 30 "DLL Generation of 4x Clock in Virtex-E Devices."
07/23/01	2.2	<ul style="list-style-type: none"> Made minor edits to text under Configuration. Added CLB column locations for XCV2600E and XCV3200E devices in Table 3.
11/09/01	2.3	<ul style="list-style-type: none"> Added warning under Configuration section that attempting to load an incorrect bitstream causes configuration to fail and can damage the device.
07/17/02	2.4	<ul style="list-style-type: none"> Data sheet designation upgraded from Preliminary to Production.
09/10/02	2.5	<ul style="list-style-type: none"> Added clarification to the Input/Output Block, Configuration, Boundary Scan Mode, and Block SelectRAM sections. Revised Figure 18, Table 11, and Table 36.
11/19/02	2.6	<ul style="list-style-type: none"> Added clarification in the Boundary Scan section. Removed last sentence regarding deactivation of duty-cycle correction in Duty Cycle Correction Property section.
06/15/04	2.6.1	<ul style="list-style-type: none"> Updated clickable web addresses.
01/12/06	2.7	<ul style="list-style-type: none"> Updated the Slave-Serial Mode and the Master-Serial Mode sections.
01/16/06	2.8	<ul style="list-style-type: none"> Made minor updates to Table 8.

Date	Version	Revision
07/23/01	2.2	<ul style="list-style-type: none"> Under Absolute Maximum Ratings, changed (T_{SOL}) to 220 °C. Changes made to SSTL symbol names in IOB Input Switching Characteristics Standard Adjustments table.
07/26/01	2.3	<ul style="list-style-type: none"> Removed T_{SOL} parameter and added footnote to Absolute Maximum Ratings table.
9/18/01	2.4	<ul style="list-style-type: none"> Reworded power supplies footnote to Absolute Maximum Ratings table.
10/25/01	2.5	<ul style="list-style-type: none"> Updated the speed grade designations used in data sheets, and added Table 1, which shows the current speed grade designation for each device. Added XCV2600E and XCV3200E values to DC Characteristics Over Recommended Operating Conditions and Power-On Power Supply Requirements tables.
11/09/01	2.6	<ul style="list-style-type: none"> Updated the Power-On Power Supply Requirements table.
02/01/02	2.7	<ul style="list-style-type: none"> Updated footnotes to the DC Input and Output Levels and DLL Clock Tolerance, Jitter, and Phase Information tables.
07/17/02	2.8	<ul style="list-style-type: none"> Data sheet designation upgraded from Preliminary to Production. Removed mention of MIL-M-38510/605 specification. Added link to XAPP158 from the Power-On Power Supply Requirements section.
09/10/02	2.9	<ul style="list-style-type: none"> Revised V_{IN} in Absolute Maximum Ratings table. Added Clock CLK switching characteristics to Table 2, “IOB Input Switching Characteristics,” on page 6 and IOB Output Switching Characteristics, Figure 1.
12/22/02	2.9.1	<ul style="list-style-type: none"> Added footnote regarding V_{IN} PCI compliance to Absolute Maximum Ratings table. The fastest ramp rate is 0V to nominal voltage in 2 ms
03/14/03	2.9.2	<ul style="list-style-type: none"> Under Power-On Power Supply Requirements, the fastest ramp rate is no longer a "suggested" rate.

Virtex-E Data Sheet

The Virtex-E Data Sheet contains the following modules:

- DS022-1, Virtex-E 1.8V FPGAs:
[Introduction and Ordering Information \(Module 1\)](#)
- DS022-2, Virtex-E 1.8V FPGAs:
[Functional Description \(Module 2\)](#)
- DS022-3, Virtex-E 1.8V FPGAs:
[DC and Switching Characteristics \(Module 3\)](#)
- DS022-4, Virtex-E 1.8V FPGAs:
[Pinout Tables \(Module 4\)](#)

Pinout Differences Between Virtex and Virtex-E Families

The same device in the same package for the Virtex-E and Virtex families are pin-compatible with some minor exceptions, listed in [Table 1](#).

XCV200E Device, FG456 Package

The Virtex-E XCV200E has two I/O pins swapped with the Virtex XCV200 to accommodate differential clock pairing.

XCV400E Device, FG676 Package

The Virtex-E XCV400E has two I/O pins swapped with the Virtex XCV400 to accommodate differential clock pairing.

All Devices, PQ240 and HQ240 Packages

The Virtex devices in PQ240 and HQ240 packages do not have V_{CCO} banking, but Virtex-E devices do. To achieve this, eight Virtex I/O pins (P232, P207, P176, P146, P116, P85, P55, and P25) are now V_{CCO} pins in the Virtex-E family. This change also requires one Virtex I/O or V_{REF} pin to be swapped with a standard I/O pin.

Additionally, accommodating differential clock input pairs in Virtex-E caused some IO_V_{REF} differences in the XCV400E and XCV600E devices only. Virtex IO_V_{REF} pins P215 and P87 are Virtex-E IO_V_{REF} pins P216 and P86, respectively. Virtex-E pins P215 and P87 are IO_DLL .

Table 1: Pinout Differences Summary

Part	Package	Pins	Virtex	Virtex-E
XCV200	FG456	E11, U11	I/O	No Connect
		B11, AA11	No Connect	IO_LVDS_DLL
XCV400	FG676	D13, Y13	I/O	No Connect
		B13, AF13	No Connect	IO_LVDS_DLL
XCV400/600	PQ240/HQ240	P215, P87	IO_V_{REF}	IO_LVDS_DLL
		P216, P86	I/O	IO_V_{REF}
All	PQ240/HQ240	P232, P207, P176, P146, P116, P85, P55, and P25	I/O	V_{CCO}
		P231	I/O	IO_V_{REF}

**Table 9: HQ240 Differential Pin Pair Summary
XCV600E, XCV1000E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
48	6	P56	P57	✓	-
49	6	P52	P53	✓	-
50	6	P49	P50	✓	VREF
51	6	P46	P47	✓	VREF
52	6	P41	P42	✓	-
53	6	P38	P39	✓	-
54	6	P35	P36	✓	VREF
55	6	P33	P34	1	VREF
56	7	P27	P28	✓	-
57	7	P23	P24	✓	VREF
58	7	P20	P21	✓	-
59	7	P17	P18	✓	-
60	7	P12	P13	✓	VREF
61	7	P9	P10	✓	VREF
62	7	P6	P7	✓	-
63	7	P4	P5	1	VREF

Note 1: AO in the XCV600E.

BG352 Ball Grid Array Packages

XCV100E, XCV200E, and XCV300E devices in BG352 Ball Grid Array packages have footprint compatibility. Pins labeled I_O_VREF can be used as either in all parts unless device-dependent as indicated in the footnotes. If the pin is not used as V_{REF} it can be used as general I/O. Immediately following Table 10, see Table 11 for Differential Pair information.

Table 10: BG352 — XCV100E, XCV200E, XCV300E

Bank	Pin Description	Pin #
0	IO	D22
0	IO	C23 ¹
0	IO	B24 ¹
0	IO	C22
0	IO_VREF_0_L0N_YY	D21 ²
0	IO_L0P_YY	B23
0	IO	A24 ¹
0	IO_L1N_YY	A23
0	IO_L1P_YY	D20
0	IO_VREF_0_L2N_YY	C21
0	IO_L2P_YY	B22
0	IO	B21 ¹
0	IO	C20 ¹
0	IO_L3N	B20
0	IO_L3P	A21
0	IO	D18
0	IO_VREF_0_L4N_YY	C19
0	IO_L4P_YY	B19
0	IO_L5N_YY	D17
0	IO_L5P_YY	C18
0	IO	B18 ¹
0	IO_L6N	C17
0	IO_L6P	A18
0	IO	D16 ¹
0	IO_L7N_Y	B17
0	IO_L7P_Y	C16
0	IO_VREF_0_L8N_Y	A16
0	IO_L8P_Y	D15

Table 12: BG432 — XCV300E, XCV400E, XCV600E

Bank	Pin Description	Pin #
7	IO_L132P_Y	G28
7	IO_L133N	E31
7	IO_L133P	E30
7	IO_L134N_Y	F29
7	IO_VREF_L134P_Y	F28
7	IO_L135N_Y	D31
7	IO_L135P_Y	D30
7	IO_L136N	E29
7	IO_L136P	E28
<hr/>		
2	CCLK	D4
3	DONE	AH4
NA	DXN	AH27
NA	DXP	AK29
NA	M0	AH28
NA	M1	AH29
NA	M2	AJ28
NA	PROGRAM	AH3
NA	TCK	D28
NA	TDI	B3
2	TDO	C4
NA	TMS	D29
<hr/>		
NA	VCCINT	A10
NA	VCCINT	A17
NA	VCCINT	B23
NA	VCCINT	B26
NA	VCCINT	C7
NA	VCCINT	C14
NA	VCCINT	C19
NA	VCCINT	F1
NA	VCCINT	F30
NA	VCCINT	K3
NA	VCCINT	K29
NA	VCCINT	N2
NA	VCCINT	N29

Table 12: BG432 — XCV300E, XCV400E, XCV600E

Bank	Pin Description	Pin #
NA	VCCINT	T1
NA	VCCINT	T29
NA	VCCINT	W2
NA	VCCINT	W31
NA	VCCINT	AB2
NA	VCCINT	AB30
NA	VCCINT	AE29
NA	VCCINT	AF1
NA	VCCINT	AH8
NA	VCCINT	AH24
NA	VCCINT	AJ10
NA	VCCINT	AJ16
NA	VCCINT	AK22
NA	VCCINT	AK13
NA	VCCINT	AK19
<hr/>		
0	VCCO	A21
0	VCCO	C29
0	VCCO	D21
1	VCCO	A1
1	VCCO	A11
1	VCCO	D11
2	VCCO	C3
2	VCCO	L4
2	VCCO	L1
3	VCCO	AA1
3	VCCO	AA4
3	VCCO	AJ3
4	VCCO	AH11
4	VCCO	AL1
4	VCCO	AL11
5	VCCO	AH21
5	VCCO	AL21
5	VCCO	AJ29
6	VCCO	AA28
6	VCCO	AA31

Table 14: BG560 — XCV400E, XCV600E, XCV1000E, XCV1600E, XCV2000E

Bank	Pin Description	Pin#	See Note
1	IO_L43N_Y	C5	
1	IO_VREF_L43P_Y	E7	3
1	IO_WRITE_L44N_YY	D6	
1	IO_CS_L44P_YY	A2	
2	IO	D3	
2	IO	F3	
2	IO	G1	
2	IO	J2	
2	IO_DOUT_BUSY_L45P_YY	D4	
2	IO_DIN_D0_L45N_YY	E4	
2	IO_L46P_Y	F5	
2	IO_VREF_L46N_Y	B3	3
2	IO_L47P_Y	F4	
2	IO_L47N_Y	C1	
2	IO_VREF_L48P_Y	G5	
2	IO_L48N_Y	E3	
2	IO_L49P_Y	D2	
2	IO_L49N_Y	G4	
2	IO_L50P_Y	H5	
2	IO_L50N_Y	E2	
2	IO_VREF_L51P_YY	H4	
2	IO_L51N_YY	G3	
2	IO_L52P_Y	J5	
2	IO_VREF_L52N_Y	F1	1
2	IO_L53P_Y	J4	
2	IO_L53N_Y	H3	
2	IO_VREF_L54P_Y	K5	4
2	IO_L54N_Y	H2	
2	IO_L55P_Y	J3	
2	IO_L55N_Y	K4	
2	IO_VREF_L56P_YY	L5	
2	IO_D1_L56N_YY	K3	
2	IO_D2_L57P_YY	L4	
2	IO_L57N_YY	K2	

Table 14: BG560 — XCV400E, XCV600E, XCV1000E, XCV1600E, XCV2000E

Bank	Pin Description	Pin#	See Note
2	IO_L58P_Y	M5	
2	IO_L58N_Y	L3	
2	IO_L59P_Y	L1	
2	IO_L59N_Y	M4	
2	IO_VREF_L60P_Y	N5	3
2	IO_L60N_Y	M2	
2	IO_L61P_Y	N4	
2	IO_L61N_Y	N3	
2	IO_L62P_Y	N2	
2	IO_L62N_Y	P5	
2	IO_VREF_L63P_YY	P4	
2	IO_D3_L63N_YY	P3	
2	IO_L64P_Y	P2	
2	IO_L64N_Y	R5	
2	IO_L65P_Y	R4	
2	IO_L65N_Y	R3	
2	IO_VREF_L66P_Y	R1	
2	IO_L66N_Y	T4	
2	IO_L67P_Y	T5	
2	IO_VREF_L67N_Y	T3	2
2	IO_L68P_YY	T2	
2	IO_L68N_YY	U3	
3	IO	AE3	
3	IO	AF3	
3	IO	AH3	
3	IO	AK3	
3	IO_VREF_L69P_Y	U1	2
3	IO_L69N_Y	U2	
3	IO_L70P_Y	V2	
3	IO_VREF_L70N_Y	V4	
3	IO_L71P_Y	V5	
3	IO_L71N_Y	V3	
3	IO_L72P_Y	W1	
3	IO_L72N_Y	W3	

Table 14: BG560 — XCV400E, XCV600E, XCV1000E, XCV1600E, XCV2000E

Bank	Pin Description	Pin#	See Note
NA	VCCINT	N29	
NA	VCCINT	N33	
NA	VCCINT	U5	
NA	VCCINT	U30	
NA	VCCINT	Y2	
NA	VCCINT	Y31	
NA	VCCINT	AB2	
NA	VCCINT	AB32	
NA	VCCINT	AD2	
NA	VCCINT	AD32	
NA	VCCINT	AG3	
NA	VCCINT	AG31	
NA	VCCINT	AJ13	
NA	VCCINT	AK8	
NA	VCCINT	AK11	
NA	VCCINT	AK17	
NA	VCCINT	AK20	
NA	VCCINT	AL14	
NA	VCCINT	AL22	
NA	VCCINT	AL27	
NA	VCCINT	AN25	
0	VCCO	A22	
0	VCCO	A26	
0	VCCO	A30	
0	VCCO	B19	
0	VCCO	B32	
1	VCCO	A10	
1	VCCO	A16	
1	VCCO	B13	
1	VCCO	C3	
1	VCCO	E5	
2	VCCO	B2	
2	VCCO	D1	
2	VCCO	H1	

Table 14: BG560 — XCV400E, XCV600E, XCV1000E, XCV1600E, XCV2000E

Bank	Pin Description	Pin#	See Note
2	VCCO	M1	
2	VCCO	R2	
3	VCCO	V1	
3	VCCO	AA2	
3	VCCO	AD1	
3	VCCO	AK1	
3	VCCO	AL2	
4	VCCO	AN4	
4	VCCO	AN8	
4	VCCO	AN12	
4	VCCO	AM2	
4	VCCO	AM15	
5	VCCO	AL31	
5	VCCO	AM21	
5	VCCO	AN18	
5	VCCO	AN24	
5	VCCO	AN30	
6	VCCO	W32	
6	VCCO	AB33	
6	VCCO	AF33	
6	VCCO	AK33	
6	VCCO	AM32	
7	VCCO	C32	
7	VCCO	D33	
7	VCCO	K33	
7	VCCO	N32	
7	VCCO	T33	
NA	GND	A1	
NA	GND	A7	
NA	GND	A12	
NA	GND	A14	
NA	GND	A18	
NA	GND	A20	
NA	GND	A24	

Table 20: FG676 — XCV400E, XCV600E

Bank	Pin Description	Pin #
1	IO_L40P_YY	D20
1	IO_L41N_YY	F19
1	IO_VREF_L41P_YY	C21
1	IO_L42N_YY	B22
1	IO_L42P_YY	E20
1	IO_L43N_Y	A23
1	IO_L43P_Y	D21
1	IO_WRITE_L44N_YY	C22
1	IO_CS_L44P_YY	E21
2	IO	D25 ¹
2	IO	D26
2	IO	E26
2	IO	F26
2	IO	H26 ¹
2	IO	K26 ¹
2	IO	M25 ¹
2	IO	N26 ¹
2	IO_D1	K24
2	IO_DOUT_BUSY_L45P_YY	E23
2	IO_DIN_D0_L45N_YY	F22
2	IO_L46P_YY	E24
2	IO_L46N_YY	F20
2	IO_L47P_Y	G21
2	IO_L47N_Y	G22
2	IO_VREF_L48P_Y	F24
2	IO_L48N_Y	H20
2	IO_L49P_Y	E25
2	IO_L49N_Y	H21
2	IO_L50P_YY	F23
2	IO_L50N_YY	G23
2	IO_VREF_L51P_YY	H23
2	IO_L51N_YY	J20
2	IO_L52P_YY	G24
2	IO_L52N_YY	H22
2	IO_L53P_Y	J21
2	IO_L53N_Y	G25

Table 20: FG676 — XCV400E, XCV600E

Bank	Pin Description	Pin #
2	IO_VREF_L54P_Y	G26 ²
2	IO_L54N_Y	J22
2	IO_L55P_YY	H24
2	IO_L55N_YY	J23
2	IO_L56P_YY	J24
2	IO_VREF_L56N_YY	K20
2	IO_D2_L57P_YY	K22
2	IO_L57N_YY	K21
2	IO_L58P_YY	H25
2	IO_L58N_YY	K23
2	IO_L59P_Y	L20
2	IO_L59N_Y	J26
2	IO_L60P_Y	K25
2	IO_L60N_Y	L22
2	IO_L61P_Y	L21
2	IO_L61N_Y	L23
2	IO_L62P_Y	M20
2	IO_L62N_Y	L24
2	IO_VREF_L63P_YY	M23
2	IO_D3_L63N_YY	M22
2	IO_L64P_YY	L26
2	IO_L64N_YY	M21
2	IO_L65P_Y	N19
2	IO_L65N_Y	M24
2	IO_VREF_L66P_Y	M26
2	IO_L66N_Y	N20
2	IO_L67P_YY	N24
2	IO_L67N_YY	N21
2	IO_L68P_YY	N23
2	IO_L68N_YY	N22
3	IO	P24
3	IO	P26 ¹
3	IO	R26 ¹
3	IO	T26 ¹
3	IO	U26 ¹
3	IO	W25

Table 20: FG676 — XCV400E, XCV600E

Bank	Pin Description	Pin #
0	VCCO	H10
1	VCCO	J15
1	VCCO	J14
1	VCCO	H18
1	VCCO	H17
1	VCCO	H16
1	VCCO	H15
2	VCCO	N18
2	VCCO	M19
2	VCCO	M18
2	VCCO	L19
2	VCCO	K19
2	VCCO	J19
3	VCCO	V19
3	VCCO	U19
3	VCCO	T19
3	VCCO	R19
3	VCCO	R18
3	VCCO	P18
4	VCCO	W18
4	VCCO	W17
4	VCCO	W16
4	VCCO	W15
4	VCCO	V15
4	VCCO	V14
5	VCCO	W9
5	VCCO	W12
5	VCCO	W11
5	VCCO	W10
5	VCCO	V13
5	VCCO	V12
6	VCCO	V8
6	VCCO	U8
6	VCCO	T8
6	VCCO	R9
6	VCCO	R8
6	VCCO	P9

Table 20: FG676 — XCV400E, XCV600E

Bank	Pin Description	Pin #
7	VCCO	N9
7	VCCO	M9
7	VCCO	M8
7	VCCO	L8
7	VCCO	K8
7	VCCO	J8
NA	GND	V25
NA	GND	V2
NA	GND	U17
NA	GND	U16
NA	GND	U15
NA	GND	U14
NA	GND	U13
NA	GND	U12
NA	GND	U11
NA	GND	U10
NA	GND	T17
NA	GND	T16
NA	GND	T15
NA	GND	T14
NA	GND	T13
NA	GND	T12
NA	GND	T11
NA	GND	T10
NA	GND	R17
NA	GND	R16
NA	GND	R15
NA	GND	R14
NA	GND	R13
NA	GND	R12
NA	GND	R11
NA	GND	R10
NA	GND	P25
NA	GND	P17
NA	GND	P16
NA	GND	P15

FG680 Fine-Pitch Ball Grid Array Package

XCV600E, XCV1000E, XCV1600E, and XCV2000E devices in the FG680 fine-pitch Ball Grid Array package have footprint compatibility. Pins labeled IO_VREF can be used as either in all parts unless device-dependent as indicated in the footnotes. If the pin is not used as V_{REF} it can be used as general I/O. Immediately following Table 22, see Table 23 for Differential Pair information.

Table 22: FG680 - XCV600E, XCV1000E, XCV1600E, XCV2000E

Bank	Pin Description	Pin #
0	GCK3	A20
0	IO	D35
0	IO	B36
0	IO_L0N_Y	C35
0	IO_L0P_Y	A36
0	IO_VREF_L1N_Y	D34 ¹
0	IO_L1P_Y	B35
0	IO_L2N_YY	C34
0	IO_L2P_YY	A35
0	IO_VREF_L3N_YY	D33
0	IO_L3P_YY	B34
0	IO_L4N	C33
0	IO_L4P	A34
0	IO_L5N_Y	D32
0	IO_L5P_Y	B33
0	IO_L6N_YY	C32
0	IO_L6P_YY	D31
0	IO_VREF_L7N_YY	A33
0	IO_L7P_YY	C31
0	IO_L8N_Y	B32
0	IO_L8P_Y	B31
0	IO_VREF_L9N_Y	A32 ³
0	IO_L9P_Y	D30
0	IO_L10N_YY	A31
0	IO_L10P_YY	C30
0	IO_VREF_L11N_YY	B30
0	IO_L11P_YY	D29
0	IO_L12N_Y	A30
0	IO_L12P_Y	C29

Table 22: FG680 - XCV600E, XCV1000E, XCV1600E, XCV2000E

Bank	Pin Description	Pin #
0	IO_L13N_Y	A29
0	IO_L13P_Y	B29
0	IO_VREF_L14N_YY	B28
0	IO_L14P_YY	A28
0	IO_L15N_YY	C28
0	IO_L15P_YY	B27
0	IO_L16N_Y	D27
0	IO_L16P_Y	A27
0	IO_L17N_Y	C27
0	IO_L17P_Y	B26
0	IO_L18N_YY	D26
0	IO_L18P_YY	C26
0	IO_VREF_L19N_YY	A26 ¹
0	IO_L19P_YY	D25
0	IO_L20N_Y	B25
0	IO_L20P_Y	C25
0	IO_L21N_Y	A25
0	IO_L21P_Y	D24
0	IO_L22N_YY	A24
0	IO_L22P_YY	B23
0	IO_VREF_L23N_YY	C24
0	IO_L23P_YY	A23
0	IO_L24N_Y	B24
0	IO_L24P_Y	B22
0	IO_L25N_Y	E23
0	IO_L25P_Y	A22
0	IO_L26N_YY	D23
0	IO_L26P_YY	B21
0	IO_VREF_L27N_YY	C23
0	IO_L27P_YY	A21
0	IO_L28N_Y	E22
0	IO_L28P_Y	B20
0	IO_LVDS_DLL_L29N	C22
0	IO_VREF	D22 ²
1	GCK2	D21

Table 22: FG680-XCV600E, XCV1000E, XCV1600E, XCV2000E

Bank	Pin Description	Pin #
5	IO_L166P_YY	AV26
5	IO_L166N_YY	AW27
5	IO_L167P_Y	AU26
5	IO_L167N_Y	AV27
5	IO_L168P_Y	AT26
5	IO_L168N_Y	AW28
5	IO_L169P_YY	AU27
5	IO_L169N_YY	AV28
5	IO_L170P_YY	AW29
5	IO_VREF_L170N_YY	AT27
5	IO_L171P_Y	AW30
5	IO_L171N_Y	AU28
5	IO_L172P_Y	AV30
5	IO_L172N_Y	AV29
5	IO_L173P_YY	AW31
5	IO_VREF_L173N_YY	AU29
5	IO_L174P_YY	AV31
5	IO_L174N_YY	AT29
5	IO_L175P_Y	AW32
5	IO_VREF_L175N_Y	AU30 ³
5	IO_L176P_Y	AW33
5	IO_L176N_Y	AT30
5	IO_L177P_YY	AV33
5	IO_VREF_L177N_YY	AU31
5	IO_L178P_YY	AT31
5	IO_L178N_YY	AW34
5	IO_L179P_Y	AV32
5	IO_L179N_Y	AV34
5	IO_L180P_Y	AU32
5	IO_L180N_Y	AW35
5	IO_L181P_YY	AT32
5	IO_VREF_L181N_YY	AV35
5	IO_L182P_YY	AU33
5	IO_L182N_YY	AW36
5	IO_L183P_Y	AT33
5	IO_VREF_L183N_Y	AV36 ¹

Table 22: FG680-XCV600E, XCV1000E, XCV1600E, XCV2000E

Bank	Pin Description	Pin #
5	IO_L184P_Y	AU34
5	IO_L184N_Y	AU36
6	IO	W39
6	IO	AR37
6	IO	AR39
6	IO_L185N_YY	AR36
6	IO_L185P_YY	AT38
6	IO_L186N_Y	AR38
6	IO_L186P_Y	AP36
6	IO_VREF_L187N	AT39 ¹
6	IO_L187P	AP37
6	IO_L188N	AP38
6	IO_L188P	AP39
6	IO_VREF_L189N_Y	AN36
6	IO_L189P_Y	AN38
6	IO_L190N_YY	AN37
6	IO_L190P_YY	AN39
6	IO_L191N	AM36
6	IO_L191P	AM38
6	IO_L192N_Y	AM37
6	IO_L192P_Y	AL36
6	IO_VREF_L193N_YY	AM39
6	IO_L193P_YY	AL37
6	IO_L194N_YY	AL38
6	IO_L194P_YY	AK36
6	IO_VREF_L195N	AL39 ³
6	IO_L195P	AK37
6	IO_L196N	AK38
6	IO_L196P	AJ36
6	IO_VREF_L197N_YY	AK39
6	IO_L197P_YY	AJ37
6	IO_L198N_YY	AJ38
6	IO_L198P_YY	AH37
6	IO_L199N	AJ39
6	IO_L199P	AH38

Table 24: FG860 — XCV1000E, XCV1600E, XCV2000E

Bank	Pin Description	Pin #
2	IO_D1_L87N_YY	P2
2	IO_D2_L88P_YY	P3
2	IO_L88N_YY	L4
2	IO_L89P_Y	P1
2	IO_L89N_Y	R2
2	IO_L90P_Y	M5
2	IO_L90N_Y	R3
2	IO_L91P_Y	M4
2	IO_L91N_Y	R1
2	IO_L92P	N4
2	IO_L92N	T2
2	IO_L93P_Y	P5
2	IO_L93N_Y	T3
2	IO_VREF_L94P_Y	P4
2	IO_L94N_Y	T1
2	IO_L95P_YY	U2
2	IO_L95N_YY	R4
2	IO_L96P_Y	U3
2	IO_L96N_Y	T5
2	IO_L97P_Y	T4
2	IO_L97N_Y	V2
2	IO_VREF_L98P_YY	U5
2	IO_D3_L98N_YY	V3
2	IO_L99P_YY	V1
2	IO_L99N_YY	V5
2	IO_L100P_Y	W2
2	IO_L100N_Y	V4
2	IO_L101P_Y	W5
2	IO_L101N_Y	W1
2	IO_VREF_L102P_YY	Y2
2	IO_L102N_YY	W4
2	IO_L103P_YY	Y1
2	IO_L103N_YY	Y5
2	IO_VREF_L104P_Y	AA1 ¹
2	IO_L104N_Y	Y4
2	IO_L105P_YY	AA4
2	IO_L105N_YY	AA2

Table 24: FG860 — XCV1000E, XCV1600E, XCV2000E

Bank	Pin Description	Pin #
3	IO	AB4
3	IO	AC2
3	IO	AD1
3	IO	AE3
3	IO	AF4
3	IO	AH5
3	IO	AJ2
3	IO	AL1
3	IO	AM3
3	IO	AP3
3	IO	AR5
3	IO	AU4
3	IO	AB2
3	IO_L106P_Y	AB3
3	IO_VREF_L106N_Y	AC4 ¹
3	IO_L107P_YY	AB1
3	IO_L107N_YY	AC5
3	IO_L108P_YY	AD4
3	IO_VREF_L108N_YY	AC3
3	IO_L109P_Y	AC1
3	IO_L109N_Y	AD5
3	IO_L110P_Y	AE4
3	IO_L110N_Y	AD3
3	IO_L111P_YY	AE5
3	IO_L111N_YY	AD2
3	IO_D4_L112P_YY	AE1
3	IO_VREF_L112N_YY	AF5
3	IO_L113P_Y	AE2
3	IO_L113N_Y	AG4
3	IO_L114P_Y	AG5
3	IO_L114N_Y	AF1
3	IO_L115P_YY	AH4
3	IO_L115N_YY	AF2
3	IO_L116P_Y	AF3
3	IO_VREF_L116N_Y	AJ4
3	IO_L117P_Y	AG1

Table 24: FG860 — XCV1000E, XCV1600E, XCV2000E

Bank	Pin Description	Pin #
6	IO_VREF_L245N_Y	AB40 ¹
6	IO_L245P_Y	AC39
7	IO	F38
7	IO	H40
7	IO	H41
7	IO	J42
7	IO	K39
7	IO	L42
7	IO	N40
7	IO	T40
7	IO	U40
7	IO	V38
7	IO	W42
7	IO	Y42
7	IO	AA42
7	IO_L246N_YY	AA41
7	IO_L246P_YY	AB39
7	IO_L247N_Y	Y41
7	IO_VREF_L247P_Y	AA39 ¹
7	IO_L248N_YY	Y40
7	IO_L248P_YY	Y39
7	IO_L249N_YY	Y38
7	IO_VREF_L249P_YY	W41
7	IO_L250N_Y	W40
7	IO_L250P_Y	W39
7	IO_L251N_Y	W38
7	IO_L251P_Y	V41
7	IO_L252N_YY	V39
7	IO_L252P_YY	V40
7	IO_L253N_YY	V42
7	IO_VREF_L253P_YY	U39
7	IO_L254N_Y	U41
7	IO_L254P_Y	U38
7	IO_L255N_Y	U42
7	IO_L255P_Y	T39
7	IO_L256N_YY	T41

Table 24: FG860 — XCV1000E, XCV1600E, XCV2000E

Bank	Pin Description	Pin #
7	IO_L256P_YY	T38
7	IO_L257N_Y	R39
7	IO_VREF_L257P_Y	T42
7	IO_L258N_Y	R42
7	IO_L258P_Y	R38
7	IO_L259N	R40
7	IO_L259P	P39
7	IO_L260N_Y	R41
7	IO_L260P_Y	P38
7	IO_L261N_Y	P42
7	IO_L261P_Y	N39
7	IO_L262N_Y	P40
7	IO_L262P_Y	M39
7	IO_L263N_YY	P41
7	IO_L263P_YY	M38
7	IO_L264N_YY	N42
7	IO_VREF_L264P_YY	L39
7	IO_L265N_Y	L38
7	IO_L265P_Y	N41
7	IO_L266N_YY	K40
7	IO_L266P_YY	M42
7	IO_L267N_YY	M40
7	IO_VREF_L267P_YY	K38
7	IO_L268N_Y	M41
7	IO_L268P_Y	J40
7	IO_L269N_Y	J39
7	IO_VREF_L269P_Y	L40
7	IO_L270N_YY	J38
7	IO_L270P_YY	L41
7	IO_L271N_YY	K42
7	IO_VREF_L271P_YY	H39
7	IO_L272N_Y	K41
7	IO_L272P_Y	H38
7	IO_L273N_Y	J41
7	IO_L273P_Y	G40
7	IO_L274N_YY	H42
7	IO_L274P_YY	G39

**Table 29: FG1156 Differential Pin Pair Summary:
XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
311	7	P2	R8	2600 2000 1000	-
312	7	N1	R9	3200 2600 2000	-
313	7	R10	P4	3200 2600 1600 1000	-
314	7	N2	P8	3200 2600 2000 1600 1000	-
315	7	P7	P6	3200 2600 2000 1600	-
316	7	N4	M1	2600 2000 1000	VREF
317	7	N3	N6	3200 1600 1000	-
318	7	M2	P9	2600 1600	-
319	7	M3	N7	3200 2600 1600 1000	-
320	7	M4	P10	2000 1000	-
321	7	N8	L1	3200 2600 2000	-
322	7	N9	L2	3200 2600 2000 1600 1000	-
323	7	K1	M7	2000 1600 1000	VREF
324	7	L4	M8	3200 1600 1000	-
325	7	L5	J1	3200 2600 2000 1600 1000	-
326	7	K3	J2	3200 2600 2000 1600 1000	VREF
327	7	J3	L7	3200 2600 1600 1000	-
328	7	H2	M9	3200 2600 1600	-
329	7	K6	J4	2600 1000	VREF
330	7	G2	L8	3200 2600 2000 1600 1000	-

**Table 29: FG1156 Differential Pin Pair Summary:
XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
331	7	K7	H3	2000 1600	-
332	7	J5	G3	3200 2600 2000 1600 1000	VREF
333	7	H5	L9	2600 2000 1000	-
334	7	H4	J6	3200 2600 2000	-
335	7	K8	G4	3200 2600 1600 1000	-
336	7	F2	J7	3200 2600 2000 1600 1000	-
337	7	L10	F3	3200 2600 2000 1600	-
338	7	H6	E1	2600 2000 1000	VREF
339	7	E2	G5	3200 2600 1600 1000	-
340	7	D1	K9	2600 1600	-
341	7	J8	E3	3200 2600 1600 1000	VREF
342	7	D2	E4	2600 2000 1000	-
343	7	D3	F4	3200 2600 2000	-